Preferred Device

SWITCHMODE™ Series NPN Silicon Power Transistors

The MJE13009 is designed for high-voltage, high-speed power switching inductive circuits where fall time is critical. They are particularly suited for 115 and 220 V SWITCHMODE applications such as Switching Regulators, Inverters, Motor Controls, Solenoid/Relay drivers and Deflection circuits.

Features

- V_{CEO(sus)} 400 V and 300 V
- Reverse Bias SOA with Inductive Loads @ $T_C = 100$ °C
- Inductive Switching Matrix 3 to 12 Amp, 25 and 100°C t_c @ 8 A, 100°C is 120 ns (Typ)
- 700 V Blocking Capability
- SOA and Switching Applications Information
- Pb-Free Package is Available*

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Collector-Emitter Voltage		V _{CEO(sus)}	400	Vdc
Collector–Emitter Voltage		V _{CEV}	700	Vdc
Emitter-Base Voltage		V _{EBO}	9	Vdc
Collector Current	ContinuousPeak (Note 1)	I _C	12 24	Adc
Base Current	ContinuousPeak (Note 1)	I _B	6 12	Adc
Emitter Current	ContinuousPeak (Note 1)	I _E	18 36	Adc
Total Device Dissipation @ T _C = 25°C Derate above 25°C		P _D	2 16	W W/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C		P _D	100 800	W W/°C
Operating and Storage Junction Temperature Range		T _J , T _{stg}	-65 to +150	°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.25	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 5 Seconds	TL	275	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

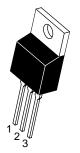
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



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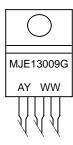
http://onsemi.com

12 AMPERE NPN SILICON POWER TRANSISTOR 400 VOLTS – 100 WATTS



TO-220AB CASE 221A-09 STYLE 1

MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week

G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
MJE13009	TO-220	50 Units / Rail
MJE13009G	TO-220 (Pb-Free)	50 Units / Rail

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	S (Note 2)					
Collector–Emitter Sustaining Voltage (I _C = 10 mA, I _B = 0)		V _{CEO(sus)}	400	_	-	Vdc
Collector Cutoff Current $(V_{CEV} = Rated \ Value, \ V_{BE(off)} = 1.5 \ Vdc)$ $(V_{CEV} = Rated \ Value, \ V_{BE(off)} = 1.5 \ Vdc, \ T_C = 100^{\circ}C)$		I _{CEV}	- -	- -	1 5	mAdc
Emitter Cutoff Current (V _{EB} = 9 Vdc, I _C = 0)		I _{EBO}	_	_	1	mAdc
SECOND BREAKDOWN						
	ector Current with base forward biased with Base Reverse Biased	I _{S/b}	See Figure 1 See Figure 2			
ON CHARACTERISTICS	(Note 2)					
DC Current Gain ($I_C = 5$ Adc, $V_{CE} = 5$ V ($I_C = 8$ Adc, $V_{CE} = 5$ V		h _{FE}	8 6		40 30	
Collector–Emitter Saturation Voltage $ \begin{aligned} &(I_C=5 \text{ Adc, } I_B=1 \text{ Adc}) \\ &(I_C=8 \text{ Adc, } I_B=1.6 \text{ Adc}) \\ &(I_C=12 \text{ Adc, } I_B=3 \text{ Adc}) \\ &(I_C=8 \text{ Adc, } I_B=1.6 \text{ Adc, } T_C=100^{\circ}\text{C}) \end{aligned} $		V _{CE(sat)}	- - - -	- - - -	1 1.5 3 2	Vdc
Base–Emitter Saturation Voltage ($I_C = 5$ Adc, $I_B = 1$ Adc) ($I_C = 8$ Adc, $I_B = 1.6$ Adc) ($I_C = 8$ Adc, $I_B = 1.6$ Adc, $I_C = 100^{\circ}$ C)		V _{BE(sat)}	- - -	- - -	1.2 1.6 1.5	Vdc
DYNAMIC CHARACTER	ISTICS					
Current–Gain – Bandwidth Product (I _C = 500 mAdc, V _{CE} = 10 Vdc, f = 1 MHz)		f _T	4	-	_	MHz
Output Capacitance $(V_{CB} = 10 \text{ Vdc}, I_E = 0, f = 0.1 \text{ MHz})$		C _{ob}	_	180	ı	pF
SWITCHING CHARACTE	RISTICS					
Resistive Load (Table 1)					
Delay Time	$(V_{CC} = 125 \text{ Vdc}, I_C = 8 \text{ A},$	t _d	_	0.06	0.1	μs
Rise Time		t _r	-	0.45	1	μs
Storage Time	$I_{B1} = I_{B2} = 1.6 \text{ A}, t_p = 25 \text{ μs},$ Duty Cycle $\leq 1\%$)	ts	_	1.3	3	μs
Fall Time		t _f	-	0.2	0.7	μs
Inductive Load, Clampe	ed (Table 1, Figure 13)					
Voltage Storage Time	(I _C = 8 A, V _{clamp} = 300 Vdc,	t _{sv}	-	0.92	2.3	μs
Crossover Time	$I_{B1} = 1.6 \text{ A}, V_{BE(off)} = 5 \text{ Vdc}, T_{C} = 100 ^{\circ}\text{C})$	t _c	_	0.12	0.7	μS

^{2.} Pulse Test: Pulse Width = 300 μs, Duty Cycle = 2%.

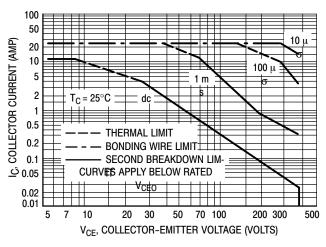


Figure 1. Forward Bias Safe Operating Area

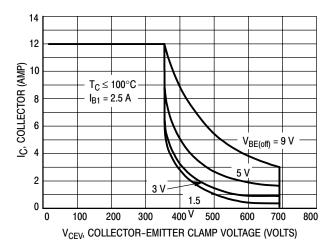


Figure 2. Reverse Bias Switching Safe Operating Area

The Safe Operating Area figures shown in Figures 1 and 2 are specified ratings for these devices under the test conditions shown.

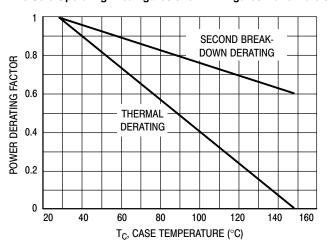


Figure 3. Forward Bias Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 1 is based on $T_C = 25^{\circ}C$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \ge 25^{\circ}C$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 1 may be found at any case temperature by using the appropriate curve on Figure 3.

 $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown. Use of reverse biased safe operating area data (Figure 2) is discussed in the applications information section.

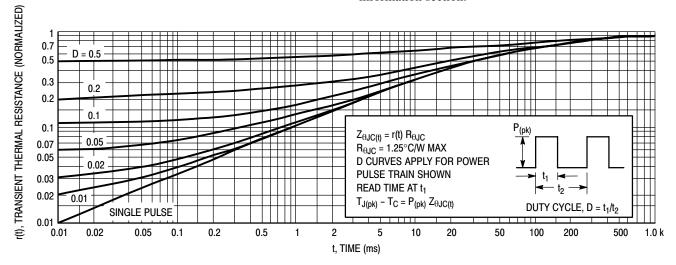


Figure 4. Typical Thermal Response $[Z_{\theta,JC}(t)]$

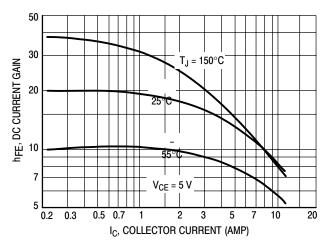


Figure 5. DC Current Gain

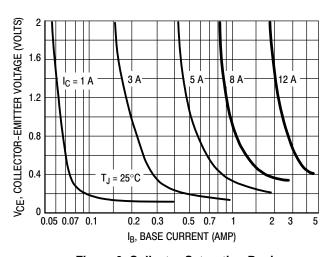


Figure 6. Collector Saturation Region

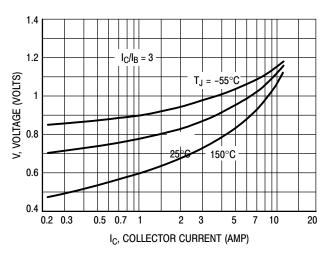


Figure 7. Base-Emitter Saturation Voltage

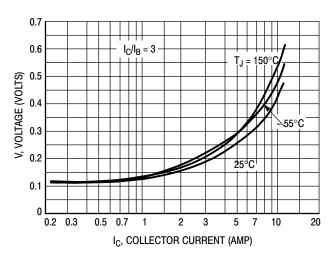


Figure 8. Collector–Emitter Saturation Voltage

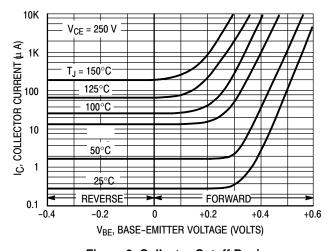


Figure 9. Collector Cutoff Region

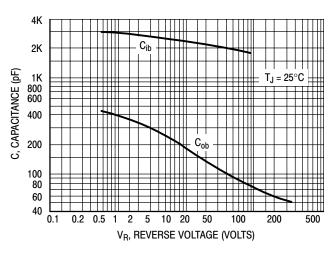
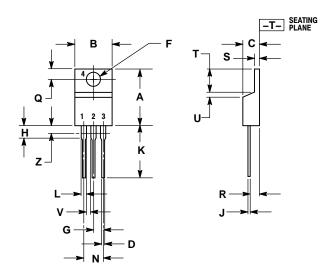


Figure 10. Capacitance

PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 **ISSUE AA**



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.018	0.025	0.46	0.64	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
T	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Z		0.080		2.04	

STYLE 1:

PIN 1. BASE

- 2. COLLECTOR
- 3. EMITTER
- COLLECTOR

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